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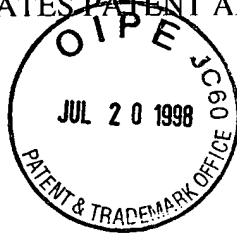
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Konecni, et al.

Serial No: 08/988,686

Filed: 12/11/97



TI-22166

RECEIVED

Examiner: JBD 23 1998

Art Unit: TDD GROUP 2100

For: METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.56

Asst. Commissioner of Patents

Washington, DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner of Patents, Washington, D.C. 20231.

Tommy Chambers

Date

Tommy Chambers 7/14/98

An attached FORM 1449 includes a list of documents which Applicants believe are relevant to the subject patent application. A copy of each citation is enclosed with the FORM 1449. Submission of these references does not constitute an admission that these papers were publications prior to the filing of the instant application. Applicants submit these references to aid the Examiner in the examination of this application.

This Information Disclosure Statement is submitted prior to the mailing of a first Office Action on the merits pursuant to 37 C.F.R. § 1.97(b).

Please charge any fees in connection with the filing of this paper, including extension of time fees, to the Deposit Account No. 20-0668 of Texas Instruments Incorporated. This form is submitted in triplicate.

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Respectfully submitted,

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